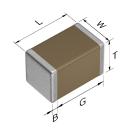
积层贴片陶瓷片式电容器

C2012JB1H684M125AB

RoHS Reach Halogen Free Pb Free

交货型号	C2012JB1H684MT****
用途	一般等级
特点	General 一般(~75V)
系列	C2012 [EIA 0805]
状态	▲ 量产体制(新设计非推荐)



尺寸			
长度(L)	2.00mm ±0.20mm		
宽度(W)	1.25mm ±0.20mm		
厚度(T)	1.25mm ±0.20mm		
端子宽度(B)	0.20mm Min.		
端子间隔(G)	0.50mm Min.		
推荐焊盘布局(PA)	1.00mm to 1.30mm(Flow Soldering)		
1世存产益41月10(11五)	0.90mm to 1.20mm(Reflow Soldering)		
推荐焊盘布局(PB)	1.00mm to 1.20mm(Flow Soldering)		
] 世 伊 / 广 · 血 / 印 / 印 (I · D)	0.70mm to 0.90mm(Reflow Soldering)		
推荐焊盘布局(PC)	0.80mm to 1.10mm(Flow Soldering)		
1年447年1年7月1年1日1日1日1日1日1日1日1日1日1日1日1日1日1日1日1日1日1日1	0.90mm to 1.20mm(Reflow Soldering)		

电·	气特性
电容	680nF ±20%
额定电压	50VDC
温度特性	JB(±10%)
耗散因数(Max.)	5%
绝缘电阻 (Min.)	735M Ω

	其他	
焊接方法	流体	
汗 依万亿	回流	
AEC-Q200	NO	
包装形式	塑封编带(180mm卷筒)	
包装个数	2000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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特性图表(这是参考数据,并不保证产品的特性。)

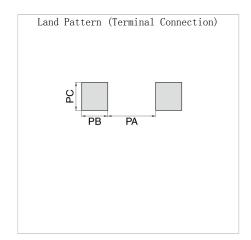
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Associated Images



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